

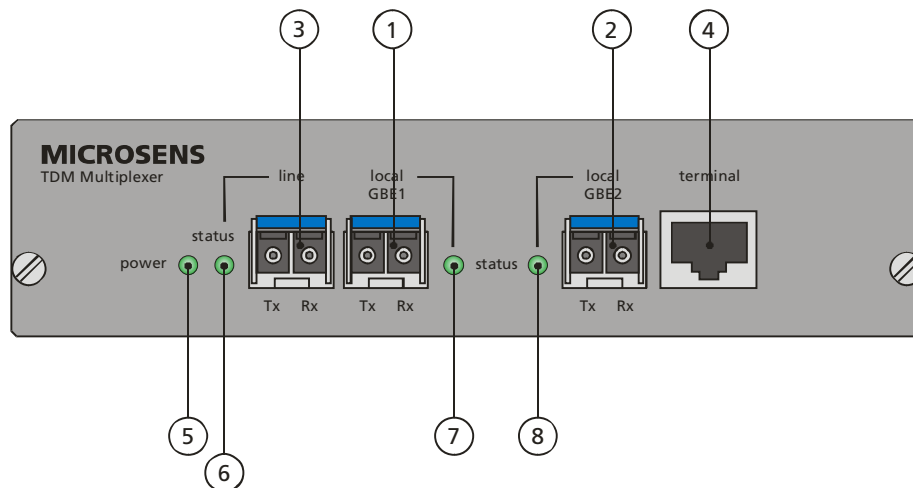
TDM Multiplexer Module

2x Gigabit Ethernet

MICROSENS

Description

Time division Multiplexing (TDM) module for the transport of two independent Gigabit Ethernet Channels on one optical 2.5 gbps channel.



Interface Description

- 1 Local Interface 1, 1000Base-X, SFP connector
- 2 Local Interface 2, 1000Base-X, SFP connector
- 3 Line Interface, 2.488 gbps (OC-48), SFP connector
- 4 Terminal Interface, RS-232, Craft Interface
- 5 Power LED
- 6 Status LED Line Interface
- 7 Status LED Local Interface 1
- 8 Status LED Local Interface 1

Technical Specifications

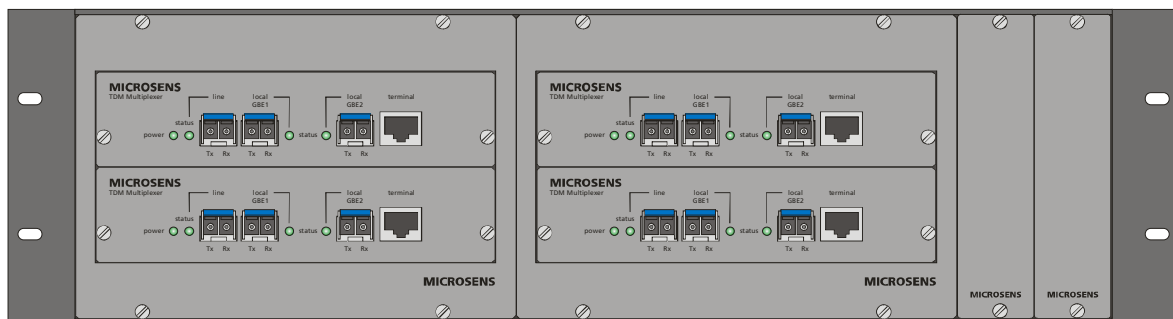
Type	Time Division Multiplexing (TDM) Module for MICROSENS modular chassis system		
Function	Transparent multiplexing of 2 independent Gigabit Ethernet channels on one single 2.5 gbps fiber port.		
Interfaces	2x local Gigabit Ethernet 1000Base-X (SFP) 1x line 2.5 gbps (SFP) 1x terminal port (RS-232) for local craft terminal (9600 bps, 8N1, VT100 emulation)		
LED Display	<i>Name</i>	<i>Color</i>	<i>Description</i>
	Power	green	Normal operation
		green, blink	Loopback on port
		red	Module or transceiver failure Transceiver missing
		off	Module not powered
	Line status	green	Normal operation
		yellow	Far-end LOS
		red	Loss-Of-Signal (LOS) Transceiver failure
		off	No link on port
	Local status 1&2	green	Normal operation
		yellow	GBE far-end LOS Transmission corrupted
		red	GBE LOS Transceiver failure
Adapter Chassis	For mounting the TDM module in MICROSENS 3U Modular Access Platform chassis. Size (w x h): 6 slots x 3 U		
Power Supply	12 V DC, max. 15 W via backplane		
Operating temp.	0°C to 55°C		
Storage temp.	-20°C to 80°C		
Rel. humidity	5% to 80% non condensing		

Installation

For the Installation into a 3 U or 4 U Modular Access Platform chassis, the Adapter Chassis must be used.

Each Adapter Chassis occupies 6 Slots of the total 14 Slots available and can hold 2 TDM Modules.

A total of 4 TDM Modules can be installed into a 14 Slots chassis, leaving 2 slots available.



Order Information

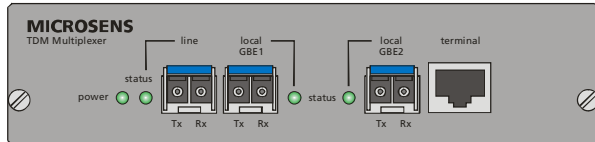
Article-No. Description

MS416440M
TDM Multiplexer Module

TDM Multiplexer Module for installation into Adapter chassis

Interfaces

- 2x SFP (local, 1000Base-X)
- 1x SFP (line, 2.448 gbps)
- 1x RJ-45 (RS-232 Terminal)



MS416048
Blind cover for unused slots

Blind cover plate for unused TDM slots in adapter chassis

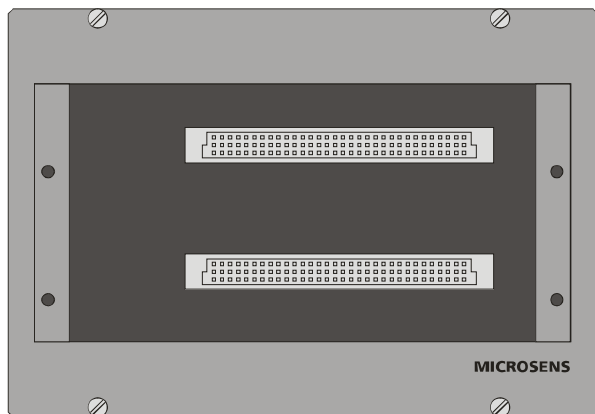


MS416049
Adapter chassis 3U for 2 TDM modules

Adapter Chassis for 3U Modular Access Platform.

Width: 6 Slots

Height: 3 U



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